





160V NPN HIGH VOLTAGE TRANSISTOR PowerDI[®]5

Features and Benefits

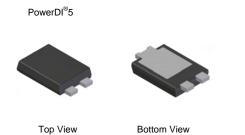
- 43% smaller than SOT223; 60% smaller than TO252
- Maximum height just 1.1mm
- Rated up to 2.25W
- BV_{CEO} > 160V
- I_{C(cont)} = 0.6A
- Lead Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free, "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

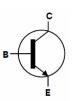
Applications

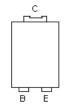
• Telecom line driver

Mechanical Data

- Case: PowerDI[®]5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 [®]
- Weight: 0.093 grams (approximate)







Device Schematic

Pin-out diagram

Ordering Information (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DXT5551P5-13	DXT5551	13	16	5,000

Notes:

- 1. No purposefully added lead.
- 2. Halogen and Antimony Free. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com

Marking Information



DXT5551 = Product Type Marking Code

Oli = Manufacturers' Code Marking

K = Factory Designator

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 09 for 2009)

WW = Week code (01 - 53)





Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	180	V
Collector-Emitter Voltage	V_{CEO}	160	V
Emitter-Base Voltage	V_{EBO}	6	V
Continuous Collector Current	Ic	600	mA

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P _D	2.25	W
Thermal Resistance, Junction to Ambient Air (Note 4)	$R_{ heta JA}$	55.5	°C/W
Power Dissipation (Note 5)	PD	1.28	W
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ heta JA}$	97.4	°C/W
Power Dissipation (Note 6)	PD	0.7	W
Thermal Resistance, Junction to Ambient Air (Note 6)	$R_{ heta JA}$	179	°C/W
Thermal Resistance, Junction to Collector Terminal	$R_{ heta JT}$	30	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

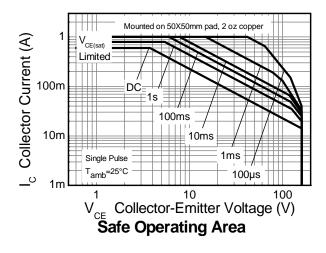
Notes:

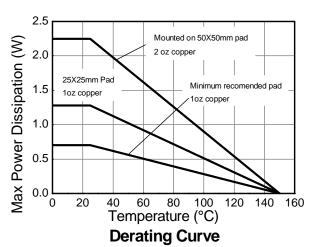
- 4. Device mounted on 1.6mm FR-4 PCB, single sided 2 oz. copper, collector pad dimensions 50mm x 50mm. 5. Device mounted on 1.6mm FR-4 PCB, single sided 1 oz. copper, collector pad dimensions 25mm x 25mm.
- 6. Device mounted on 1.6mm FR-4 PCB, single sided 1 oz. copper, minimum recommended pad layout.

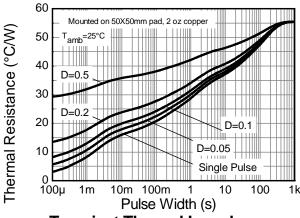


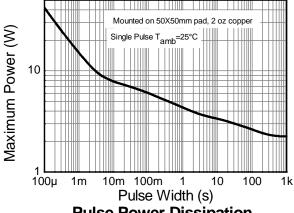


Thermal Characteristics









Transient Thermal Impedance

Pulse Power Dissipation



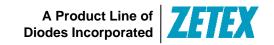


Electrical Characteristics @TA = 25°C unless otherwise specified

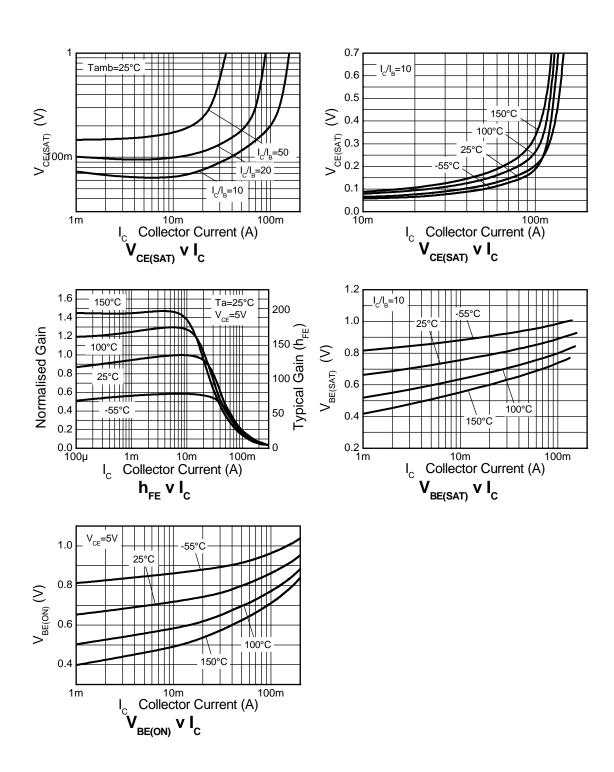
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	180	270	ı	V	$I_C = 100\mu A$
Collector-Emitter Breakdown Voltage (Note 7)	BV_{CEO}	160	200	-	V	$I_C = 1mA$
Emitter-Base Breakdown Voltage	BV _{EBO}	6.0	7.85	1	V	$I_E = 10\mu A$
Collector Cutoff Current	I _{CBO}	- -	<1 -	50 50	nA μA	V _{CB} = 120V V _{CB} = 120V, T _A = 100°C
Collector-Emitter Saturation Voltage (Note 7)	V _{CE(sat)}	- -	65 115	150 200	mV mV	$I_C = 10$ mA, $I_B = 1$ mA $I_C = 50$ mA, $I_B = 5$ mA
Base-Emitter Saturation Voltage (Note 7)	V _{BE(sat)}	- -	760 840	1000 1200		$I_C = 10$ mA, $I_B = 1$ mA $I_C = 50$ mA, $I_B = 5$ mA
DC Current Gain (Note 7)	h _{FE}	80 80 30	130 145 65	_ 250 _	I	$V_{CE} = 5V, I_{C} = 1mA$ $V_{CE} = 5V, I_{C} = 10mA$ $V_{CE} = 5V, I_{C} = 50mA$
Transition Frequency	f _T	-	130	ı	MHz	$V_{CE} = 10V, I_{C} = 10mA,$ f = 100MHz
Output Capacitance (Note 7)	C_{obo}	-	ī	6	рF	$V_{CB} = 10V$, $f = 1MHz$
Delay Time	t _(d)	-	95	ī	ns	
Rise Time	t _(r)	-	64	1	Ns	$V_{CC} = 510V, I_{C} = 10mA,$
Storage Time	t _(S)	-	1256	ı	ns	$I_{B1} = I_{B2} = 1mA$
Delay Time	t _(f)	=	140	=	ns	

Notes: 7. Pulse Test: Pulse width $\leq 300 \mu s$. Duty cycle $\leq 2.0\%$.





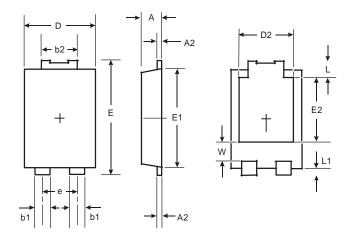
Typical Characteristics





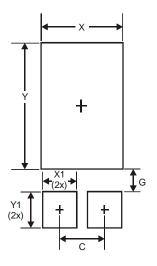


Package Outline Dimensions



PowerDI [®] 5				
Dim	Min	Max		
Α	1.05	1.15		
A2	0.33	0.43		
b1	0.80	0.99		
b2	1.70	1.88		
D	3.90	4.05		
D2	3.054 Typ			
E	6.40	6.60		
е	1.84 Typ			
E1	5.30	5.45		
E2	3.549 Typ			
L	0.75	0.95		
L1	0.50	0.65		
W	1.10	1.41		
All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
С	1.840
G	0.852
Х	3.360
X1	1.390
Y	4.860
Y1	1.400





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